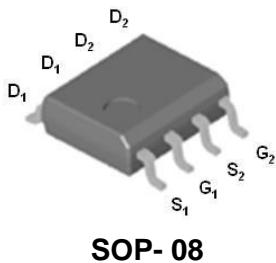


## P2103HVG

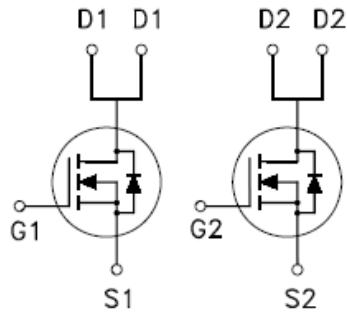
### Dual N-Channel Enhancement Mode MOSFET

#### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
30V	21mΩ @ $V_{GS} = 10V$	8A



SOP- 08



#### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current	$T_A = 25^\circ C$	$I_D$	8	A
	$T_A = 70^\circ C$		6	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	40	A
Avalanche Current		$I_{AS}$	26	
Avalanche Energy <sup>2</sup>	$L = 0.1mH$	$E_{AS}$	35	mJ
Power Dissipation	$T_A = 25^\circ C$	$P_D$	2	W
	$T_A = 70^\circ C$		1.28	
Junction & Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C

#### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$			62.5	°C / W
Junction-to-Lead		$R_{\theta JL}$		25	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup> $V_{DD} = 15V$ . Starting  $T_J = 25^\circ C$ .

## P2103HVG

### Dual N-Channel Enhancement Mode MOSFET

#### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

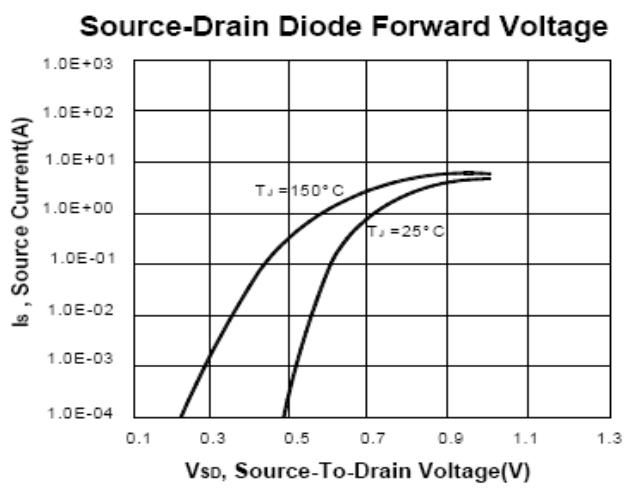
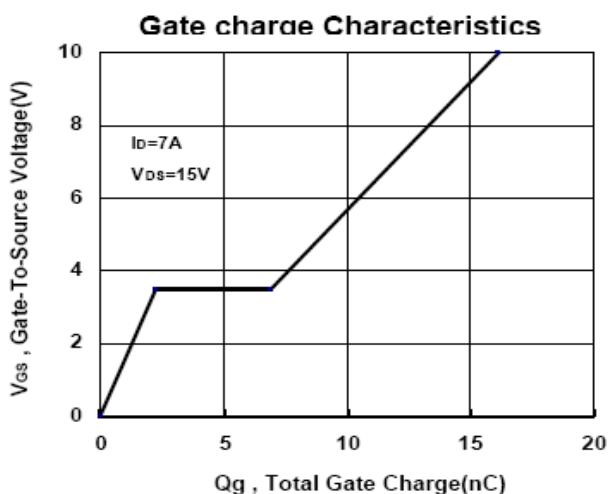
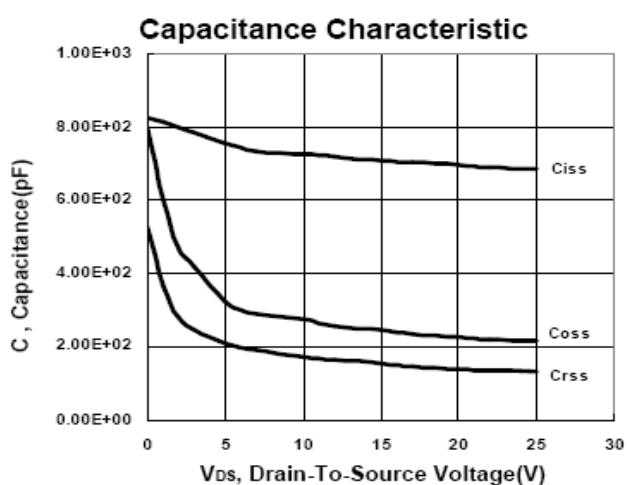
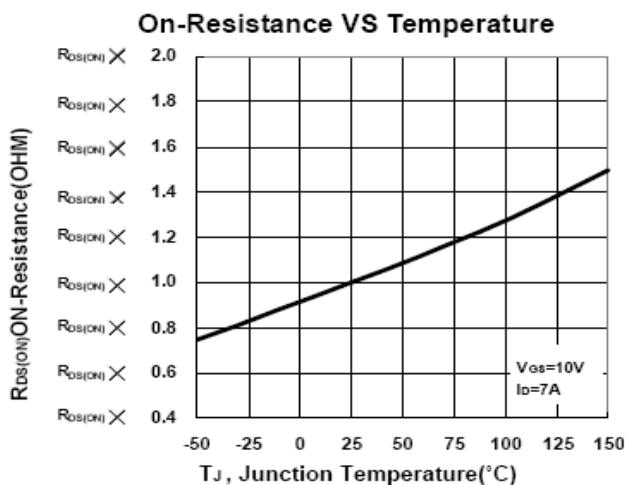
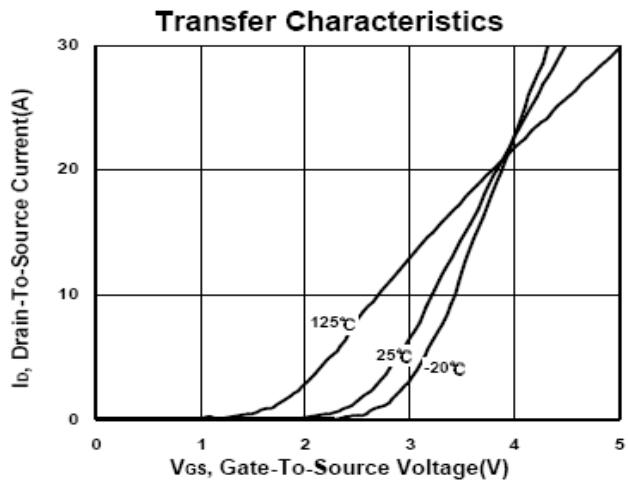
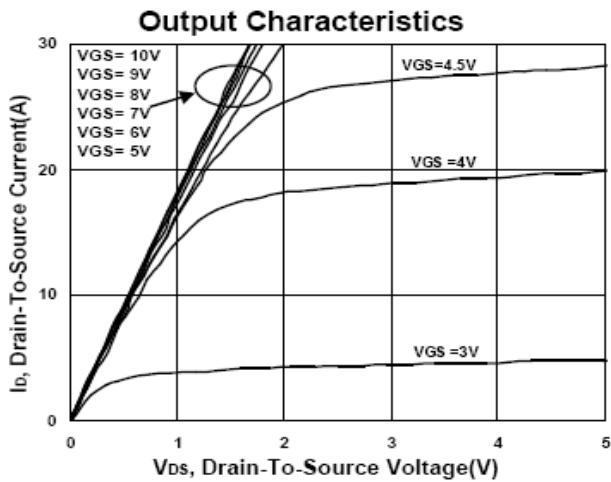
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.8	1.7	2.5	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
On-State Drain Current <sup>1</sup>	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 10\text{V}$	40			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 6\text{A}$		22	32	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 7\text{A}$		14.5	21	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 7\text{A}$		15		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 20\text{V}, f = 1\text{MHz}$		700		pF
Output Capacitance	$C_{\text{oss}}$			218		
Reverse Transfer Capacitance	$C_{\text{rss}}$			136		
Gate Resistance	$R_g$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.7		$\Omega$
Total Gate Charge <sup>2</sup>	$Q_{\text{g}(\text{VGS}=10\text{V})}$	$V_{\text{DS}} = 0.5V_{(\text{BR})\text{DSS}}, V_{\text{GS}} = 10\text{V}, I_D = 7\text{A}$		16		nC
	$Q_{\text{g}(\text{VGS}=4.5\text{V})}$			7		
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			2		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			5		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d}(\text{on})}$			5		
Rise Time <sup>2</sup>	$t_r$	$V_{\text{DS}} = 20\text{V}, R_L = 1\Omega$ $I_D \approx 7\text{A}, V_{\text{GS}} = 10\text{V}, R_G = 6\Omega$		4		nS
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d}(\text{off})}$			19		
Fall Time <sup>2</sup>	$t_f$			4		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				2	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = 7\text{A}, V_{\text{GS}} = 0\text{V}$			1	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 7\text{A}, dI_F/dt = 100\text{A} / \mu\text{s}$		18		nS
Reverse Recovery Charge	$Q_{\text{rr}}$			9		nC

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

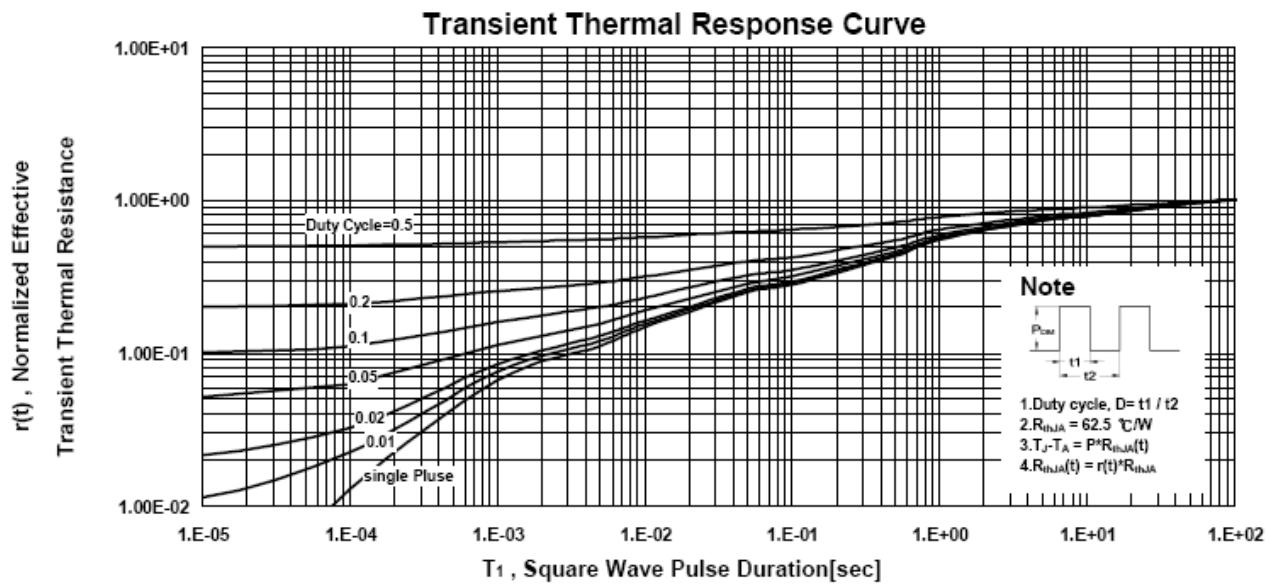
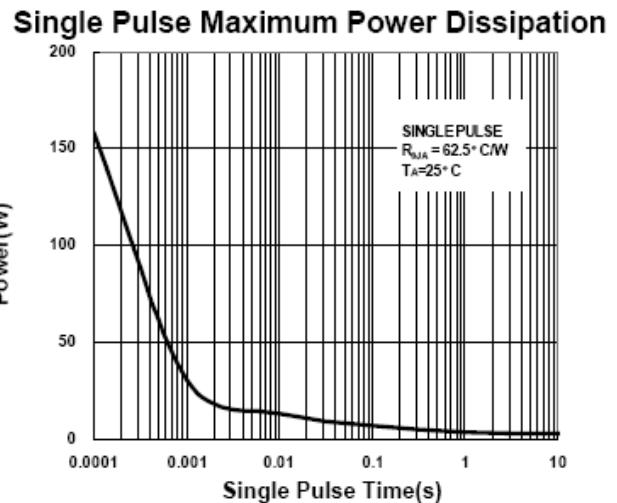
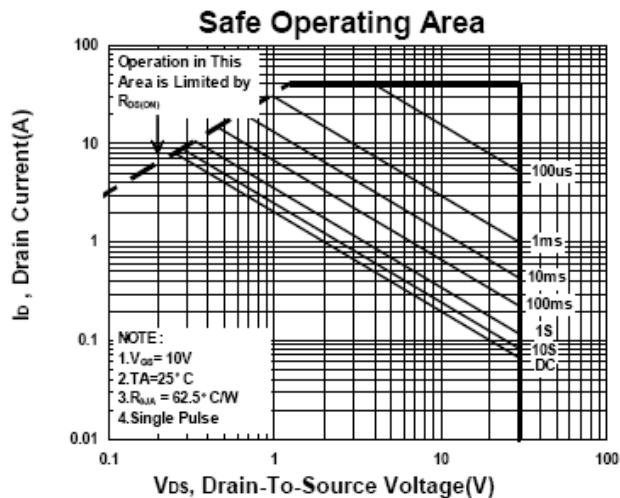
## P2103HVG

### Dual N-Channel Enhancement Mode MOSFET



## P2103HVG

### Dual N-Channel Enhancement Mode MOSFET



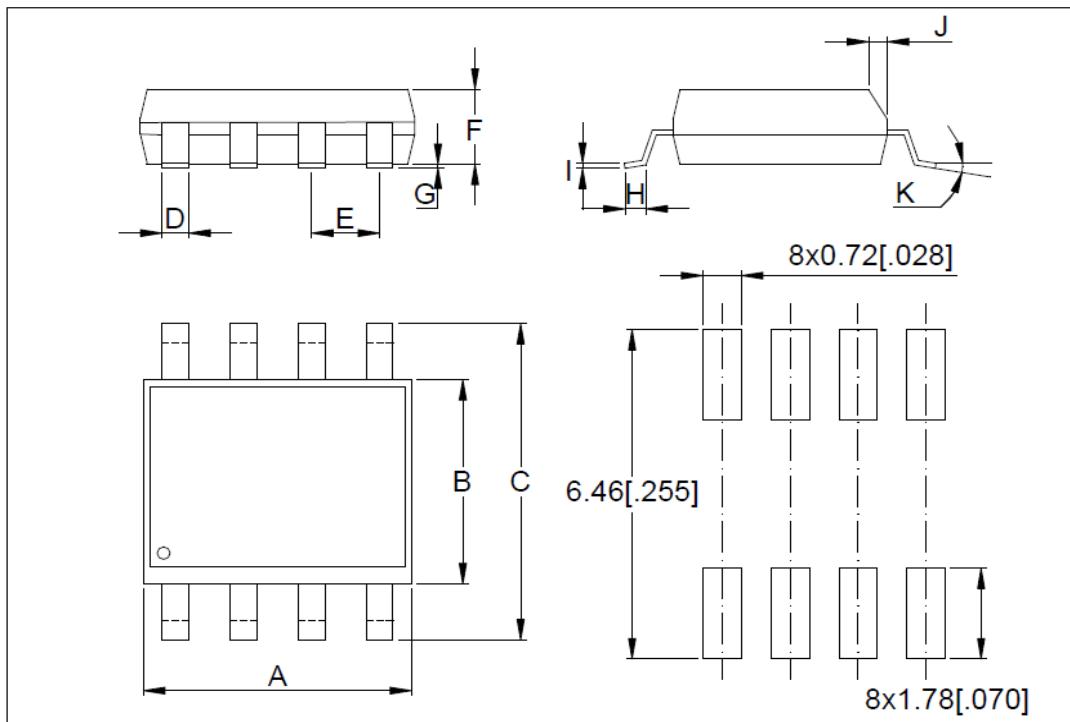
# P2103HVG

## Dual N-Channel Enhancement Mode MOSFET

### Package Dimension

### SOP-8 MECHANICAL DATA

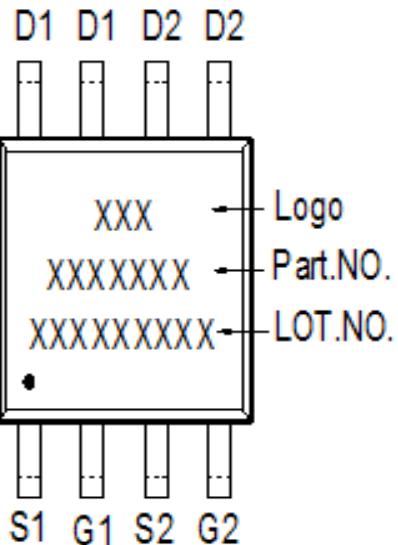
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25				



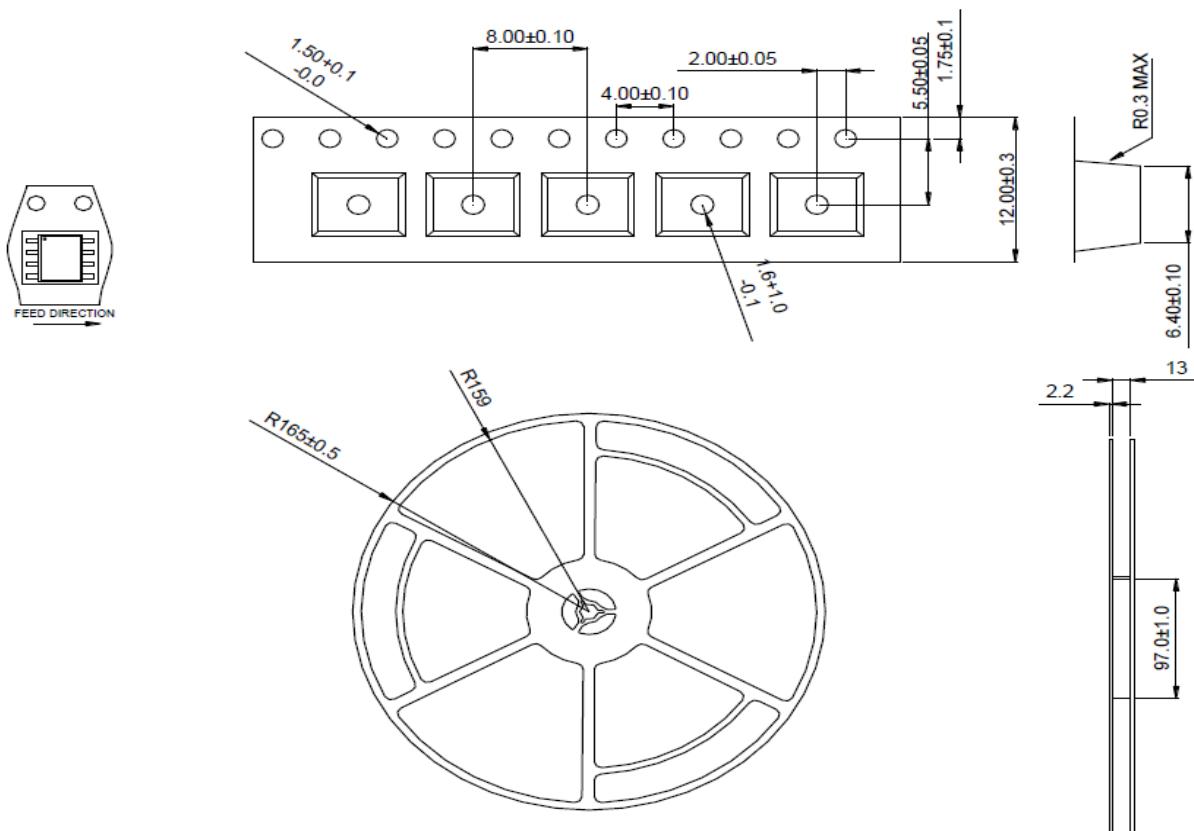
## P2103HVG

### Dual N-Channel Enhancement Mode MOSFET

#### A. Marking Information



#### B. Tape&Reel Information: 2500pcs/Reel



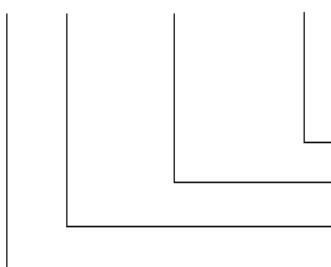
## P2103HVG

### Dual N-Channel Enhancement Mode MOSFET

#### C. Lot.No. & Date Code rule

##### 1. LOT.NO.

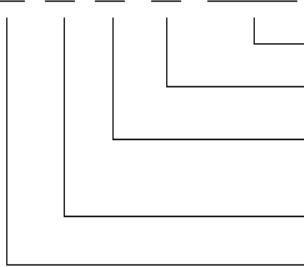
M N 15M21 03



- #8~9 Sub-lot No
- Order series no.
- Foundry site
- Assembly site

##### 2. Date Code

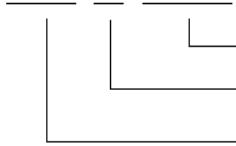
D Y M X XXX



- Order series no. & Sub-lot No
- Week
- M : Month (A:Jan , B:Feb , C:Mar ,D :Apr ,E:May ,F:Jun,G:Jul,H:Aug,I:Sep,J:Oct,K:Nov,L:Dec.)
- Y : Year (N : 2011, O : 2012 ...)
- Assembly site

##### 3. Date Code (for Small package)

XX Y WW



- Week
- Y : Year (9: 2009,A : 2010, B : 2011 ...)
- Device Name

## P2103HVG

### Dual N-Channel Enhancement Mode MOSFET

#### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least